ADAPTIVE SAMPLING FOR ENHANCED PERFORMANCE OF AN ION DETECTION -- ETC
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ADAPTIVE SAMPLING FOR ENHANCED PERFORMANCE OF
AN ION DETECTION SYSTEM FOR
A TRIPLE QUADRUPOLE MASS SPECTROMETER

by

R.S. Matthews, C.G. Enke, and P.D. Fisher

Presented as an MSEE Thesis

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ABSTRACT

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Detection and tabulation of mass-selected ions are the primary means of data acquisition for mass spectrometers. Previous detection systems have been limited in dynamic range, or in data throughput, so that inefficient and limited use of the ion information resulted.

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*** TABLE OF CONTENTS ***

<table>
<thead>
<tr>
<th>LIST OF FIGURES</th>
<th>page</th>
</tr>
</thead>
<tbody>
<tr>
<td>I. INTRODUCTION</td>
<td></td>
</tr>
<tr>
<td>1.1 Mass Spectrometry Overview</td>
<td>1</td>
</tr>
<tr>
<td>1.2 Triple Quadrupole Mass Spectrometer (TQMS)</td>
<td>2</td>
</tr>
<tr>
<td>1.3 Ion Detection System (IDS)</td>
<td>3</td>
</tr>
<tr>
<td>1.4 Thesis Organization</td>
<td>7</td>
</tr>
<tr>
<td>II. DESIGN REQUIREMENTS</td>
<td>9</td>
</tr>
<tr>
<td>2.1 Input Characteristics</td>
<td>10</td>
</tr>
<tr>
<td>2.1.1 Dynamic Range</td>
<td>11</td>
</tr>
<tr>
<td>2.1.2 Acquisition Speed and Sampling Precision</td>
<td>13</td>
</tr>
<tr>
<td>2.2 Control and Interfacing</td>
<td>16</td>
</tr>
<tr>
<td>2.3 Other Considerations</td>
<td>19</td>
</tr>
<tr>
<td>2.3.1 Outputs</td>
<td>19</td>
</tr>
<tr>
<td>2.3.2 Noise</td>
<td>20</td>
</tr>
<tr>
<td>2.3.3 Physical Deployment</td>
<td>20</td>
</tr>
<tr>
<td>2.3.4 Stability and Reliability</td>
<td>21</td>
</tr>
<tr>
<td>2.3.5 Cost</td>
<td>21</td>
</tr>
<tr>
<td>III. HARDWARE</td>
<td>22</td>
</tr>
<tr>
<td>3.1 Hardware Overview</td>
<td>22</td>
</tr>
<tr>
<td>3.2 Detection Unit (DU)</td>
<td>24</td>
</tr>
<tr>
<td>3.2.1 Dual-Mode Channeltron</td>
<td>26</td>
</tr>
<tr>
<td>3.2.2 Support Circuitry</td>
<td>28</td>
</tr>
<tr>
<td>3.2.3 Housing</td>
<td>31</td>
</tr>
<tr>
<td>3.3 Processing Unit (PU)</td>
<td>32</td>
</tr>
<tr>
<td>3.3.1 Pulse Channel Circuitry</td>
<td>32</td>
</tr>
<tr>
<td>3.3.2 Analog Channel Overview</td>
<td>36</td>
</tr>
<tr>
<td>3.3.3 Current-to-Voltage Converter</td>
<td>37</td>
</tr>
<tr>
<td>3.3.4 Integration Circuit</td>
<td>39</td>
</tr>
<tr>
<td>3.3.5 A/D Converter</td>
<td>43</td>
</tr>
<tr>
<td>3.3.6 System Timer/Counter (STC)</td>
<td>44</td>
</tr>
<tr>
<td>3.3.7 Analog Control Outputs</td>
<td>47</td>
</tr>
<tr>
<td>3.3.8 PU Support Logic</td>
<td>48</td>
</tr>
<tr>
<td>3.3.9 Miscellaneous Circuitry</td>
<td>51</td>
</tr>
<tr>
<td>3.4 Control Unit (CU)</td>
<td>52</td>
</tr>
<tr>
<td>3.4.1 Central Processing Unit</td>
<td>53</td>
</tr>
<tr>
<td>3.4.2 Memory</td>
<td>53</td>
</tr>
<tr>
<td>3.4.3 Block Selects (Address Decoding)</td>
<td>55</td>
</tr>
<tr>
<td>3.4.4 Dual USARTs</td>
<td>55</td>
</tr>
<tr>
<td>3.4.5 Interrupt Controller</td>
<td>56</td>
</tr>
<tr>
<td>3.4.6 CU-PU Interface</td>
<td>56</td>
</tr>
<tr>
<td>3.4.7 Multi-Micro Interface</td>
<td>57</td>
</tr>
</tbody>
</table>

iv
IV. SOFTWARE

4.1 Languages
4.1.1 FORTH
4.1.2 8085 Assembly Language
4.1.3 Structure

4.2 Command Classifications
4.2.1 Elementary Functions
4.2.2 Data Processing
4.2.3 Calibration
4.2.4 High-Speed Control
4.2.5 Standard Control
4.2.6 Development

4.3 Numeric Representation
4.3.1 Internal Representations
4.3.2 I/O Representations

V. EVALUATION

5.1 Sampling Simulation
5.2 Processing Unit (PU) Performance
5.2.1 C/V Converter
5.2.2 Integration Circuit
5.2.3 A/D Converter
5.2.4 STC
5.2.5 Other PU Circuits

5.3 Control Unit (CU) Performance
5.3.1 Software
5.3.2 Hardware

5.4 General Observations
5.4.1 Noise Immunity
5.4.2 Stability and Reliability
5.4.3 Usability

VI. SUMMARY

6.1 Achievement Of Goals
6.2 Further Improvements
6.3 Conclusions

APPENDICES
A. Processing Unit (PU) Calculations
B. IDS Command Glossary
C. Firmware Source Code

BIBLIOGRAPHY
**LIST OF FIGURES**

1.1 Typical Mass Spectrometer .................................................. 4
1.2 Triple Quadrupole Mass Spectrometer (TQMS) .......................... 5
1.3 Sample spectra ........................................................................ 8
2.1 Relationship between ion flux, integration period, and error ... 15
2.2 TQMS Automated Control Structure ........................................ 18
3.1 Ion Detection System (IDS) block diagram ............................ 23
3.2 Detection Unit (DU) block diagram ........................................ 25
3.3 Dual-Mode Channeltron Characteristics ................................. 27
3.4 Control circuit for Detection Unit (DU) ................................. 29
3.5 Processing Unit (PU) block diagram ....................................... 33
3.6 Pulse Channel Circuitry ......................................................... 34
3.7 Analog Channel block diagram ............................................... 38
3.8 Current-to-Voltage (C/V) Converter Circuit ......................... 40
3.9 Integrator Circuit ................................................................. 42
3.10 A/D Converter Circuit .......................................................... 45
3.11 System Timer/Counter (STC) configuration ........................... 46
3.12 PU Support Logic --- Local Decoding Circuit ....................... 49
3.13 PU Support Logic --- Control Circuit .................................... 50
3.14 Control Unit (CU) block diagram ......................................... 54
4.1 IDS Memory Map ..................................................................... 62
<table>
<thead>
<tr>
<th>Section</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>4.2 Coordinating Program structure</td>
<td>63</td>
</tr>
<tr>
<td>4.3 Data Processing Command example</td>
<td>67</td>
</tr>
<tr>
<td>4.4 Data formats</td>
<td>75</td>
</tr>
<tr>
<td>5.1 Simulation program</td>
<td>79</td>
</tr>
<tr>
<td>5.2 C/V Converter and Integrator Circuit performance</td>
<td>80</td>
</tr>
</tbody>
</table>
The use of microprocessor-based instrumentation, such as by the Mass Spectrometry Research Group at Michigan State University, has become the basis for the continuing development of several advanced spectroscopy techniques. The flexibility, speed, and overall cost-performance benefits offered by microprocessor-based instrumentation in real-time control and data acquisition applications are central to the successful development of one such technique: Triple Quadrupole Mass Spectrometry.

This thesis describes the conceptualization and implementation of a portion of the instrumentation for the Triple Quadrupole Mass Spectrometer (TQMS) at MSU: a microprocessor-based Ion Detection System. The Ion Detection System (IDS) performs the key function of data acquisition for the TQMS using an adaptive sampling technique for enhanced performance.

The remainder of this chapter provides brief descriptions of mass spectrometry, the TQMS, the purpose of the IDS, and an outline of the subsequent chapters on the IDS development and realization.
1.1 MASS SPECTROMETRY OVERVIEW

In order to derive information describing the chemical composition of a substance, chemists may employ one or more of a variety of analytical techniques. Spectroscopy is one such class of techniques; spectra relating various atomic and molecular properties of a substance are used in classifying the substance.

Of all the spectroscopic techniques available to an analytic chemist, mass spectrometry is one of the most versatile because of the wide range of information it can provide [1]. "The analysis of a substance by mass spectrometry involves the conversion of a sample into atomic or molecular ions and subsequent separation of these ions on the basis of their mass-to-charge ratio by magnetic or electrostatic means. Projected ions are selected according to their mass characteristics and are recorded as a function of abundance; the resulting spectrum is characteristic of the original sample" [2].

"Modern mass spectrometers are constructed from elements which approach the state-of-the-art in vacuum systems, magnetic and electrostatic field generation, precision machining, solid-state electronics, and computerized data acquisition and processing. These instruments find applications in studies as diverse as biomolecules, petrochemicals, pharmocology, geochemistry, forensic chemistry, and the environment" [2].
A mass spectrometer can be viewed as composed of four major components: the ion source and its associated inlet, the mass analyzer, the vacuum system, and the ion detector. Figure 1.1 depicts a typical mass spectrometer and its major components [3]. The following section describes the TQMS (first developed at MSU) and provides further insight into the functioning of a mass spectrometer.

1.2 TRIPLE QUADRUPOLE MASS SPECTROMETER (TQMS)

The TQMS (Triple Quadrupole Mass Spectrometer) was originally developed for analytical applications by Yost and Enke during the late 1970s [4]. Figure 1.2 depicts the TQMS. Since contamination of the sample or of the generated ions would result in an erroneous characterization, special consideration is given to the design of the operating environment of the TQMS. Central to this design is the enclosure of the components within a tightly controlled vacuum (10^-7 torr). Also, since large electrostatic potentials across relatively small dimensions are required, vacuum failure could result in destructive arcing. As a result, vacuum system design is critical.

A sample is converted to atomic or molecular ions within the ion source. These ions are extracted and focused by electrostatic potentials into a beam which is directed toward the mass analyzer section.
Figure 1.1  Typical Mass Spectrometer [3]
The mass analyzer section of the TQMS distinguishes it from other types of mass spectrometers. The first quadrupole mass filter separates the incoming ion beam such that all ions of a selected mass value (amu) are passed into the quad collision chamber; ions of all other masses are filtered out. This filtering is achieved through the interaction of DC and RF electrostatic fields supplied through the quadrupoles with the mass-charge ratio of the incoming ion beam [5].

In the quad collision chamber, an inert gas is introduced such that the incoming ions fragment upon collision with the inert gas molecules. A quadrupole is used as the collision chamber to provide continued focusing of the ion beam. This collision chamber provides an added dimension in analysis by enabling characterization of substances which are composed of large, complex molecules. A final quadrupole mass filter separates the incoming ion fragments for detection of ion abundance (as a function of mass) by the ion detector.

Most modern mass spectrometers employ an electron multiplier to perform the ion detection. The energy of the incident ions upon the first part of the multiplier's dynode chain is converted into secondary electrons, which upon subsequent collisions with the dynodes generate increasing numbers of electrons. Gains up to $10^7$ are routinely obtained (the multiplier acts as a charge amplifier, with
each incoming ion representing one unit of charge). For ion flux determinations, the multiplier's output is encoded in the time domain as current pulses, or if the incident ion rate is faster than the response time of the multiplier, as an analog current. The TQMS was originally equipped with a standard Channeltron-type of electron multiplier [6]. Though the standard Channeltron performed acceptably, it presented obstacles towards the full potential realization of the TQMS.

1.3 ION DETECTION SYSTEM (IDS)

The ion abundance, or more accurately the ion flux, incident upon the detector is correlated with the pass values of the mass filters to generate the characterization spectra; a sample spectra is given in Figure 1.3. The absolute ion flux is a function of several parameters of the TQMS and of the input sample; as a result, the absolute flux may range over many orders of magnitude. Since electron multipliers are physically limited in their dynamic range, active controls are evoked over detector operation to position this limited range "window" over the absolute range of the data. This creates added difficulties for detection system design and spectrometer operation, the details of which are discussed in Chapter 2.

A need to maximize range, accuracy, efficiency, proficiency, and simplicity of TQMS operation provides a
continuing impetus for the TQMS operators/designers to subject the instrument to a variety of component enhancements utilizing state-of-the-art technologies. Current major enhancement projects include the development of microprocessor-based control and data acquisition systems (the TQMS Multi-Micro System [7]), and an on-line computerized data processing and storage system. These objectives spurred the development of an enhanced ion detection system capable of operation within a sophisticated control environment.

1.4 THESIS OUTLINE

This thesis describes the IDS from its conceptualization to its realization. Chapter 2 explores in detail the set of design constraints imposed upon the IDS design, emphasizing the statistical considerations which form the basis for an adaptive sampling algorithm. Chapters 3 and 4 describe the specifics of the chosen implementation; Chapter 3 concentrates on the electronic and mechanical hardware, while Chapter 4 discusses the microprocessor software structure and programs. Chapter 5 evaluates the IDS performance, and Chapter 6 offers a general summary. Appendices are included which provide information on hardware and software pertinent to an IDS user.
The main function of the IDS is to detect ions directed toward its input and relay the number of ions per second (ion flux) detected to the TQMS data processing/storage system in an appropriate format. The TQMS user also requires very rapid data collection with minimum error and with minimal manual user interaction. In order to maximize these attributes, the design of the IDS is carefully correlated to a large number of TQMS operating parameters. The physical and statistical characteristics of the input sample(s) and its various ionic representations, the limitations of the mass spectrometer and its supporting instrumentation, and the interface to the TQMS control and data processing systems are all prime considerations in the IDS design. These factors in combination with the ever-present considerations of environment, reliability, cost, and simplicity of use are weighed against each other in establishing design requirements implementable with available technology. The following sections develop the key IDS design criteria.

2.1 INPUT CHARACTERISTICS

Performance of the IDS is fundamentally limited by factors characteristic of the ion input; analysis of the
interrelation of these factors provides the insight required for development of an "optimal" detection system. The three most critical factors are the dynamic range, the acquisition speed, and the sampling error.

2.1.1 Dynamic Range

Theoretically, information useable for spectra generation resides in ion flux levels ranging from the infinitesimal to the infinite. In reality, ion flux is limited on the low end by noise produced by the TQMS in the form of stray ions and on the high end by the saturation of sensitive source and detection components. These limitations are common to all types of mass spectrometers.

Some mass spectrometer applications require as little as two decades of dynamic range. Standard detection apparatus can provide up to four decades of range, sufficient for a majority of present applications. Since a sample is characterized not by the absolute, but rather by the relative ion flux per mass point, adjustments in source emission and/or detector sensitivity can provide expansion of the dynamic range beyond the limitations of the detector. Without going into details, this method results in degradation of calibration accuracy and system throughput.

The TQMS is presently designed to limit noise ions to 1 ips (ions per second), thus defining the low end of the
dynamic range (a 2:1 signal-to-noise ratio is acceptable in some analysis modes). Incident ion rates of 1 billion ips will saturate nearly all commercially available electron multipliers. Thus an absolute dynamic range of $10^0$ to $10^9$ ips is established.

At low ion flux levels (typically less than $10^6$ ips), the response time of an electron multiplier is sufficient to permit pulse counting, provided the multiplier is operated at near its maximum gain (typically $10^7$). Analog current measurement of the multiplier output is used when pulse overlap occurs for flux levels above $10^6$ ips; in this case, the gain is reduced to prevent saturation. Gain is achieved through the application of large voltages across highly resistive dynodes.

Most present detection systems have opted to use only one type of output, reducing control and hardware requirements at the expense of limiting spectrometer performance. Those that opt for pulse counting reduce data throughput since high flux rates (which are quickly measured by analog techniques) require down-scaling and a corresponding increased sampling period. Strictly analog detection systems cannot accurately detect the tiny currents produced at low flux levels; increasing the emission rate of the ion source is often restricted due to the limited amounts of available sample. Thus the design of an optimal
detection system requires hardware capable of processing both pulse and analog signals.

2.1.2 Acquisition Speed and Sampling Precision

Because the data acquired (ion flux) by the IDS is based upon the occurrence of random events (ions detected), there is a strict dependency between the time taken to acquire a single piece of data and its resulting relative precision. One characteristic is improved at the expense of the other. The basic argument goes as follows:

Statistical laws predict the magnitude of deviations about an average value, i.e., white noise variation about a "DC" signal such as the "average" ion count [8,9]. The standard deviation for a random count is:

$$\text{SD} = \sqrt{\text{COUNT}}$$

Similarly, for a count rate (ion flux):

$$\text{SD}^\prime = \left(\text{COUNT} / \text{TIME}\right)^\frac{1}{2} = \sqrt{\text{FLUX}}$$

The percent relative standard deviation is defined as the "typical" (within one standard deviation) error:

$$\text{ERROR} = \pm \left(\sqrt{\text{FLUX} / \text{FLUX}}\right) \times 100\% = \pm \left(\text{FLUX}\right)^\frac{1}{2} \times 100\%$$

This inverse relationship between the flux and the error defines the fundamental limits of data acquisition.
parameters. For example, as the number of ions counted over a fixed interval increases, the error decreases (and vice versa). Suppose that ions are being detected over a 1 second interval. If 100 ions are detected, then:

\[
\text{ERROR} = \pm (100) \times 100\% = 10\%
\]

Suppose 1,000,000 ions are detected; then,

\[
\text{ERROR} = \pm (1,000,000) \times 100\% = 0.1\%.
\]

Conversely, specification of the allowable error determines the minimum number of counted ions required for a given precision:

\[
\text{MINIMUM COUNT} = \left( \frac{\text{ERROR}}{100\%} \right)^{-2} = \left( \frac{\text{10000\%}}{\text{ERROR}} \right)
\]

For example, if the error (precision) is specified as 1%,

\[
\text{MINIMUM COUNT} = \left( \frac{\text{10000\%}}{\text{1\%}} \right) = 10000 \text{ counts}
\]

Thus counting can be terminated upon satisfaction of the minimum requirement.

Summarizing, for a fixed counting interval the error varies inversely with the count rate (ion flux). Similarly, setting of the acceptable error limit permits minimization of the sampling period relative to the flux. This intricate relationship between data parameters is shown graphically in Figure 2.1.
In order to characterize large molecules, the TQMS is designed to scan samples from 1 amu to 1000 amu. Resolution of 10 parts per amu is sufficient to accurately define an ion flux peak; thus the entire domain of mass values is subdivided into 10000 portions.

The total number of ions emitted is a function of the amount of available sample and the source ionization efficiency. In cases where there are only a limited amount of ions available for filtering and detection, correspondingly quick scanning modes require very fast detection (error considerations are secondary) over a selected mass domain. With the present source, the worst case specification requires a complete scan of the entire mass domain in one second; this sets the maximum acquisition rate at 10 kHz.

Spectra with peaks defined to within 1% relative precision uniquely characterize a sample. In many types of TQMS analysis, such precision is not required. A detection system designed to sample adaptively permits the user to "trade-off" precision versus speed, since these two parameters are inversely related. The graph of Figure 2.1 clearly establishes operating points for the IDS.

2.2 CONTROL AND INTERFACING

Since data acquisition requires a great deal of flexibility on the part of the IDS in response to user
necessitated. A microprocessor-based control scheme compatible with the TQMS Multi-Micro control structure is chosen.

A block diagram of the entire TQMS automated control and data processing structure is given in Figure 2.2 [10]. Data reduction, storage, analysis, and color graphics are handled by the DEC LSI 11/23 minicomputer, independent of ongoing operations of the TQMS. The operation of the TQMS is controlled by the user through the Multi-Micro structure. The option to call upon a variety of pre-programmed operating modes, or to design customized operations is made available to the user. Operating parameters are supplied directly by the user or by the system through default.

In Figure 2.2 the IDS is represented as a single slave-microprocessor block (other slaves control the mass analyzer, vacuum, source, user interface, and other miscellaneous functions). Firmware to control the functions of the IDS exists in local memory. These functions are coordinated by software downloaded from the Multi-Micro System. This permits the user to configure the operating parameters for data acquisition without becoming involved in the time-consuming specifics related to programming the IDS; also, the IDS is relieved of storing all software except that critical to its real-time operation. Additional memory is included for temporary storage of data before transmission to the minicomputer. Also, for calibrating,
Figure 2.2 TQMS Automated Control Structure [10]
testing, and debugging purposes, specialized hardware and firmware are included in the design of the IDS. Chapters 3 and 4 examine the specifics of IDS hardware and software.

2.3 OTHER CONSIDERATIONS

Several other considerations affect the design of the IDS. Though all of the following are significant, they are simply satisfied through the selection of proper components and/or through careful applications of standard techniques.

2.3.1 Output Representations

Binary-coded representations of data collected by the IDS are required by the TQMS data processing/storage system. Since acquisition speed is a primary consideration in IDS design, most data processing is carried out by the 11/23 minicomputer, i.e., the IDS output is an integration time and this output is correlated with preset IDS operating parameters by the 11/23 to determine the actual ion flux. For development purposes, the IDS software design provides for on-board flux calculations and formatting. Analog representations are also required for monitoring and auxiliary analog data recording (x-y plotter).
2.3.2 Noise

The charge carried by an individual singly charged ion is very small (approximately $1.6 \times 10^{-19}$ coulombs). The high gain supplied by the electron multiplier still provides only a small output current (no larger than 1 uA). Subsequent processing electronics are designed to guard against unwanted noise sources through the careful application of standard shielding and grounding techniques.

Care is also taken in protecting digital signals from unwanted transients or other disturbances. Also, since some digital as well as analog signals are transmitted over relatively large distances (the reasons for this are discussed below), provisions for the proper driving and receiving of these signals are made.

2.3.3 Physical Deployment

Only two restrictions exist upon the physical deployment of the IDS. One is that the electron multiplier reside in the vacuum chamber of the TQMS. The other is that the initial amplification electronics be located as near as possible to the multiplier output so as to minimize noise and transmission losses.

The remainder of the IDS may be situated as practicality suggests. Where portions of it are separated,
transmission/reception circuitry must be included to insure reliable distanced communication.

2.3.4 Stability and Reliability

Though the enhancement of IDS stability and reliability are considerations left primarily to a second-generation IDS design, these two characteristics have not been totally disregarded. The selection of IC's, components, connectors, mounting and housing hardware, is significantly based on these elements' ability to provide stable and reliable operation against the effects of time, temperature, electrical, and environment.

2.3.5 Cost

Careful analysis of the design criteria developed in this chapter and of the available technological tools demonstrates that the IDS offers a substantial cost-performance benefit over other types of detectors. The key to the realization of this benefit lies in the proper selection and configuration of reasonably-priced hardware and software components. The specifics of the implementation chosen are detailed in the next two chapters.
The IDS hardware design allows the user to optimize various parameters associated with data acquisition through a programmable approach. The chosen implementation provides the user with ion flux data in a variety of forms dependent on the mode of IDS operation.

A top-down description is used in this chapter; the IDS is viewed first as a few general function blocks which are subsequently developed as more detailed sub-units. The following chapter on software provides additional perspective related to the threading of these sub-units.

3.1 HARDWARE OVERVIEW

The IDS is designed as three distinct functional units; this facilitates the development, testing, and conceptualization of the IDS. These units are titled: the detection unit (DU), the processing unit (PU), and the control unit (CU). Figure 3.1 presents a block diagram of the IDS showing the interconnection of its 3 main units. Interfacing specifics are detailed within appropriate sections.

Central to the operation of the IDS is the Intel 8085A microprocessor [11]. Though any type of general purpose microprocessor may suffice, the 8085 is chosen for its
Figure 3.1 Ion Detection System (IDS) block diagram
compatibility with the TQMS Multi-Micro System (which is also 8085-based). This compatibility also permits sharing of high-level software and development tools, thus reducing overhead costs.

The electronic components are mounted on several two-sided printed circuit board modules. These modules, except for the initial amplification and conversion stages (which are stand-alone boards), are soldered on several motherboards, which in turn are connected through backplanes or through ribbon cables. This type of construction enhances reliability while permitting ease in development and testing.

3.2 DETECTION UNIT (DU)

The DU is the input stage for the IDS. Ions generated and selected by the TQMS source and mass analyzer are fed to the DU. The DU converts the input ion flux into pulse or analog current for subsequent processing by the PU. Control and status inputs and outputs are also required for protection of the DU components. A block diagram of the DU is given in Figure 3.2.

At the heart of the DU is a new, enhanced type of electron multiplier: the Dual-Mode Channeltron® recently developed by the Galileo Corp [12]. This type of electron multiplier offers expanded dynamic range, $10^0$ to $10^9$, without any run-time gain scaling.
Figure 3.2 Detection Unit (DU) block diagram
Support circuitry and specialized housing comprise the remainder of the DU. Detailed discussion on the DU hardware follows.

3.2.1 Dual-Mode Channeltron

A Channeltron™ is an electron-multiplying device which is constructed with a single continuous dynode (this type of multiplier is more stable and reliable than discrete dynode types). Depending on the input ion flux and the gain setting, a pulse or analog current is output. Standard Channeltrons™ provide a single output; processing circuitry must multiplex this output if both pulse and analog techniques are required. Gain adjustments are required to expand the dynamic range beyond $10^3$ ips.

The Dual-Mode Channeltron™ provides distinct output channels for pulse and analog currents. This Channeltron™ requires an extra power supply (see Figure 3.2) to provide gain for a separate high-gain section, but no voltage ranging is required for either gain section in order to achieve full dynamic range. As a result, the limiting factor in IDS data acquisition speed and range is no longer the electron multiplier.

For brevity, the Dual-Mode Channeltron™ is henceforth referred to as the "Channeltron". Specifications on Channeltron performance are given in Figure 3.3. For ion flux levels up to $10^6$ ips, pulse outputs are valid. Above
Figure 3.3  Dual-Mode Channeltron Characteristics [12]
this level, the high-gain \((10^7)\) section of the Channeltron may saturate; a protection grid within the Channeltron is activated to prevent this. At flux levels above \(10^9\) ips the low-gain \((10^4)\) section may saturate; gain (voltage) is removed in this case. Flux levels below \(10^5\) ips are most efficiently measured by pulse-counting techniques.

3.2.2 Support Circuitry

The Channeltron receives its gain from voltage potentials applied across its highly resistive dynode. The low-gain section requires a voltage of approximately \(-1400\) V, the high-gain section requires \(+1900\) V, and the protection grid requires \(+350\) V. (If in the "protect" state; grounded if not). These voltages are supplied from three commercial high-voltage sources.

Special precautions are taken in order to assure safe Channeltron operation. If either section of the Channeltron is forced to saturate as a result of input overdrive, temporary and/or permanent degradation of operating characteristics may occur [13]. Also, if the vacuum pressure in the TQMS ever drops below a certain level, the Channeltron would be destroyed by arcing across its high-potentials.

The circuitry used to implement these precautions is shown in Figure 3.4. Because the high-voltage supply requires several minutes to bring its output to ground, a
Figure 3.4 Control circuit for detection unit (DU)
pair of high-voltage switches are needed to quickly cut-off (or turn-on) the supply voltages to the Channeltron. These switches are isolated from their control inputs, since high-voltage or large-current feedback through these inputs could damage other portions of the IDS; opto-isolators are incorporated as preventions.

Several inputs are used to control the DU high-voltage switches. Feedback of the analog output of the Channeltron, in the form of scaled voltages, is used to detect and protect against Channeltron saturation. Two such inputs, signifying low-gain and high-gain section saturation, are supplied via the PU (Processing Unit); a Channeltron output current of 10 nA is the high-gain section cut-off level, and a current of .5 uA is the overall cut-off threshold. Voltage levels of 1 V and 5 V, respectively, represent these thresholds. These voltages are fed to comparators (with hysteresis) which test them against reference voltages (see Figure 3.4). When input "H" exceeds 1 V, a +350 V signal is applied to the protection grid input of the high-gain section. When input "H" drops below 0.9 V, the protection grid input is returned to ground, permitting electrons to enter the high-gain section. Comparator "L", which controls application of the -1400 V and +1900 V used to provide Channeltron gain, is referenced to 5 V. If input "L" exceeds 5 V, the gain voltage inputs of the Channeltron are brought to ground, shutting down the Channeltron operation.
A command from the TQMS user is required to reactivate the Channeltron.

Other control inputs come from the CU (Control Unit) and from manual switches. The on/off state of the high-voltages are controlled through these inputs for purposes of restart, calibration, or testing. Manual, CU, and feedback control signals are all required to be "OK" before the Channeltron will operate.

The DU also supplies two differentially driven outputs which signal the state of the high-voltage switches. These signals inform the other IDS units which channel(s) of the DU, if either, is providing valid output. All support circuitry inputs and outputs are appropriately buffered.

3.2.3 Housing

The Channeltron is mounted inside the TQMS vacuum chamber. Channeltron inputs and outputs are fed through the back-flange of the TQMS to the remainder of the IDS. The back-flange is specially constructed to permit passage of electrical signals and supplies via BNC, MHV, and SHV connectors, thus permitting simple interface to external circuitry.

The DU support circuitry is housed in a grounded metal box which acts as shielding. Logic circuits are mounted on a printed circuit board and are physically and electrically isolated from the high-voltage switches.
3.3 PROCESSING UNIT

Conversion of the raw analog and pulse currents, supplied by the Channeltron, into data which represent the input ion flux is the primary function of the PU. This data may be in one of several forms depending on the nature of the experiment being performed. These forms are described in detail through the remainder of this section.

Two distinct channels (corresponding to the two types of input supplied to the PU by the Channeltron) form the main body of the PU; they are referred to as the pulse channel and the analog channel. Each channel converts its corresponding type of input into data or control signals required by the IDS. A block diagram of the PU is given in Figure 3.5. Details of the PU design follow.

3.3.1 Pulse Channel Circuitry

Diagrams for the pulse channel are given in Figure 3.6. The pulse channel is composed of an amplifier, a discriminator, and a counter. A commercial pulse-amplifier-discriminator, built by Galileo Corp. especially for Channeltron pulse detection, met the design requirements exactly. This device, the PAD-400 [14], is capable of resolving non-random Channeltron output pulses at rates up to 8 MHz. According to statistics associated with the counting of random events, the resolving time of the
Figure 3.5 Processing Unit (PU) block diagram
Figure 3.6 Pulse Channel Circuitry
counter and the maximum average count rate determine the probability of missing a count due to pulse overlap [15]. The probability, $P(n)$, that $n$ pulses occur within the resolving time, $t_d$, of a pulse counter is given by the Poisson distribution:

$$P(n) = \frac{[(R \cdot t_d)^n / n!]}{\exp(-R \cdot t_d)}$$

where $R$ is the average pulse rate. The probability of two or more pulses occurring within the counter resolving time is:

$$P(2+) = 1 - P(0) - P(1)$$

It is desirable that average pulse rates up to 1 MHz be counted to within 1% relative precision (this provides an operational overlap of both channels, necessary for on-line calibration). Application of the above equation shows that a 7 MHz (non-random) counter is the required minimum to insure 1% precision.

In order to record up to $10^6$ counts, the pulse counter also requires sufficient width (minimum of 20 bits). Reduction of both speed and width requirements can be attained through the addition of pre-scaling circuitry.

The counter used in the pulse channel design is part of the programmable multi-counter IC from AMD, the Am9513
System Timer/Counter (STC) [16]. A 32-bit counter within the STC is designated as the pulse counter; the counter operates up to a 7 MHz non-random rate. This IC is also used by both channels for timing purposes; a separate discussion on the (STC) is reserved for a later section.

3.3.2 Analog Channel Overview

The analog channel design requires some type of analog-to-digital conversion: input currents ranging from $10^{-10}$ to $10^{-6}$ A represent the ion flux range from $10^5$ to $10^9$ ips (see Figure 2.1). Though the Channeltron of the DU is not an exact linear amplifier, a linear model is sufficient for the purpose of analog channel design and descriptions. The non-linearity factors are accounted for in down-line CU or TQMS data processing systems.

As mentioned in the section on the DU (Detection Unit), control voltages representing Channeltron saturation are required by the DU. A direct feedback of the information contained in the analog input current is supplied from the PU; the circuitry which generates the control voltages is considered as part of the analog channel.

From analysis of the design constraints, the following conclusions are drawn relative to the analog channel design: First, the time required to collect a single piece of data (an ion flux level) is dependent upon the flux level and the acceptable error in the data (see Figure 2.1). The IDS must
wait for a sufficient number of ions to be detected before the ions per second value is valid; the acquisition throughput is limited by the data itself. Secondly, since the quality of the data may be traded off in favor of fast acquisition (or vice-versa), programmable control of the analog (and pulse) channel is required for IDS optimization.

A block diagram of the analog channel is shown in Figure 3.7. After initial conversion to a voltage, the analog input is directed along three routes. Route one takes the analog signal to a monolithic A/D converter which provides direct conversion of the input. The second route leads to a programmable integrator which, in conjunction with a timer, supplies an integration time representative of the input signal. This time is correlated with other integrator parameters to determine the ion flux. The final route leads to a pair of op-amps which feedback the analog level to the DU comparators to control the Channeltron. The details and the reasoning behind the configuration of the analog channel are explored in the following sections.

3.3.3 Current-to-Voltage Converter

Current input to the analog channel will range from approximately $10^{-10}$ to $5 \times 10^{-7}$ A. In order to facilitate subsequent analog processing, a current-to-voltage conversion is required. A standard op-amp circuit is used. The converter is set to provide an output range from 1 mV to
Figure 3.7 Analog Channel block diagram
5 V. Since even slight bias currents and offset voltages
would be catastrophic to the functioning of this circuit,
special components and construction are required.

Although an instrumentation type of op-amp could
accurately provide the required output, all presently lack
the slew rate necessary for high-speed IDS operation. A
chopper-stabilized op-amp, the ICL7650 from Intersil [17],
is selected because of its low bias, low offset, virtually
nill drift, low power consumption, good slew rate, and low
cost.

The disadvantages in using the 7650 are not
significant, but must be compensated for in the remainder of
the analog channel design. Operating voltages are limited
to ±8 V, extra capacitors are required for the chopper,
slight output noise is generated by the chopper action, and
output impedance is approximately 1KΩ. Also, a capacitor
across the feedback network is required to insure stability.

The op-amp inputs are surrounded by a guard ring to
prevent current leakage from the supply pins. Also, since
the feedback resistor is of a very large value (10MΩ), the
resistor's body is enclosed in a separate shield in order to
reduce noise pick-up. Figure 3.8 gives the circuit.

3.3.4 Integrator Circuit

The voltage output of the C/V converter is proportional
to the analog current output of the Channeltron, which is in
Figure 3.8 Current-to-Voltage (C/V) Converter Circuit
turn proportional to the ion flux. By applying the technique of single-slope integration, the flux level can be calculated from the time required to integrate this voltage to a reference value.

Figure 3.9 shows the integrator circuit. An alternative way of conceptualizing the operation of this circuitry is as follows: the Channeltron, the C/V converter, and the input resistor of the integrator form an ion-to-charge converter (assume that this converter is perfectly linear and has zero response time); the current input to the summing node of the integrator is a collection of discrete charge packets, each equivalent to a single ion. The feedback capacitor of the integrator acts as a charge counter whose output is a linearly proportional voltage. As shown in Section 2.1.2, for a specified sampling error only a minimum number of ions (or charge packets) need be counted; this "count" is divided by the total time of integration to determine the ion flux. A comparator signals a completed integration when the capacitor (charge counter) voltage has reached a reference voltage representative of the required minimum count.

As a result, data acquisition proceeds in an asynchronous manner, maximizing throughput. Maximum integration times may also be programmed for cases where throughput requirements outweigh those of accurate sampling of all data. A connection of the integrator output to an
Figure 3.9 Integrator Circuit
A/D converter is provided for evaluation of partially integrated data samples.

Precision components are required. An ICL7650 is used for the integrator's op-amp. Low leakage SPST analog switches, one-half of a DG211 [18], are used. A polystyrene capacitor minimizes dielectric retention and leakage currents. A unity-gain inverter buffers the integrator output to prevent voltage droop. Positive-feedback provides hysteresis for the comparator. A variable voltage reference is supplied by a D/A converter so that the CU (Control Unit) may adjust the analog "count" limit according to the programmed maximum error. Timing is performed by the STC (Am9513 timer/counter, see Section 3.3.6).

The integrator provides the added advantage of a low-pass filter, since input signals above 10KHz (the maximum data collection rate) are considered to be noise.

Calculations to determine the values of the components associated with this circuitry are given in Appendix A. Means for calculating the ion flux from the integration time are undertaken in Section 4.2.3.

3.3.5 A/D Converter

In some types of acquisition modes, speedy data collection is of priority, regardless of the extra error induced by the limited "counting" of random events (ion inputs). Direct measurement of the C/V converter output
voltage is a solution where even partial integrations are too slow.

A 12-bit monolithic A/D converter, the AD574 [19], performs this function. In order to provide measurement of both the C/V converter and the integrator output, these voltages are multiplexed to the A/D input; the CU supplies convert and read strobes and controls the multiplexer. Tri-state drivers buffer the output. The complete A/D circuit is shown in Figure 3.10.

An A/D conversion is also triggered upon completion of an integration; this allows the CU to perform a calibration between the reference and integrator voltages, if desired. Also, CU monitoring of the C/V converter output is useful in noise studies and in IDS development.

3.3.6 System Timer/Counter (STC)

The Am9513 System Timer/Counter (STC) times the integration periods for both analog and pulse channels, and also counts pulses for the pulse channel. Five individually programmable 16-bit counters are contained in it. These registers may be concatenated and can use a variety of gates, sources, active logic inputs, and be operated in a variety of modes.

Figure 3.11 shows an abridged block diagram of the STC internal structure as configured for this application. A 32-bit register is used for integration timing; a second
Figure 3.10 A/D Converter Circuit
Figure 3.11 System Timer/Counter (STC) configuration
32-bit register for pulse counting; and a 16-bit register for general event-counting. Programming and data retrieval for the STC is directed by the CU. Further information regarding the structuring and programming of the STC will be presented in chapter 4.

3.3.7 Analog Control Outputs

Feedback of the analog current output is supplied to the DU for controlling the operation of the Channeltron. As discussed in Section 3.2.2, signals actuating the shutdown of the gain sections are required.

The "H" amplifier outputs a 100x version of the voltage supplied by the C/V converter. An input of 10 mV (corresponding to the high-gain section overdrive level) produces a 1 V output: this activates the protection grid of the Channeltron. The "H" amp output is limited by a zener diode.

The "L" amplifier is a simple follower. If the C/V converter output reaches 5 V, shutdown of the entire Channeltron follows; restart must be explicitly commanded by the user. Both amplifiers outputs are differentially driven to the DU (Detection Unit).
3.3.8 Support Logic

The PU receives commands from the CU and status information from the DU, which properly coordinates execution of PU functions. The PU also provides various status signals to the CU. These signals are supplied and received through a potpourri of decoders, flip-flops, and gates, collectively referred to as the PU support logic.

The logic diagrams are presented in Figures 3.12 and 3.13. CU commands are sent as reads/writes to specified memory locations (memory mapped). The PU support logic decodes the address information, and except for the STC and A/D output (which require use of the CU data bus), it ignores the dummy data while providing strobe signals through the PU. Flip-flops provide control of the PU analog switches, and signal the CU with interrupt requests. A monitor port, through which the CU can read PU and DU status signals, exists as the lower 4 bits of the A/D output drivers (differential inputs are required).

Actuation of most PU functions requires direct commands from the CU. Several exceptions occur: when the integrator enters the "hold" state upon triggering of its associated comparator; while integrating, a "terminal count" (TC) signal is issued by the STC, signifying that the sampling time limit has been reached; upon a power-up reset supplied by a resistor-capacitor-schmitt-triggered gate.
Figure 3.12  PU Support Logic --- Local Decoding Circuit
Figure 3.13  PU Support Logic --- Control Circuit
Further information relating the control scheme of the PU is provided in Chapter 4.

3.3.9 Miscellaneous Circuitry

The PU requires interfacing to a group of CU lines. These include the data bus, four address lines (A3-A0), read and write, and two interrupts. Differential transceivers, configured in one and two-way modes, drive/receive these signals. An identical set of transceivers is included on the CU end.

Regulated DC power of several voltages is required for PU operation: +15, -15, +8, -8, and + V. Standard LM320/LM340 [20] series IC voltage regulators are used. Regulator inputs are supplied from regulated +24 and -24 V DC sources. Heat sinks are attached to the regulators.

The PU is constructed of three physically separable units: an analog board ("A" board), a digital board ("D" board), and the PAD-400. The "A" board is of single-piece construction with ground plane covering all unused spaces. Connection of the analog input from the Channeltron is through a coaxial cable which is connected to the TQMS back-flange on one end, and soldered directly to the "A" board on the other. A grounded metal box shields the "A" board. The "D" board is an assembly of small boards ("modules") soldered to a motherboard. PU functions are divided the "A" and "D" boards such that all low-level
signals may be processed in a low-noise environment, and that a minimum number of lines are required to interface the boards. All signals are differentially driven between the boards; connections are made through ribbon cables or twisted pairs. The "A" board is housed next to the back-flange, the "D" board is housed about three feet away in a convenient area.

3.4 CONTROL UNIT

A programmable control unit, the CU, directs the operation of the IDS. The basic functional modules used in the CU were designed by other research group members for implementation within portions of the TQMS Multi-Micro System. Incorporation of these modules into the CU provides the necessary "hooks" for linking the IDS into the Multi-Micro and data processing/storage systems.

The 8085A microprocessor and some of its family of peripheral ICs form the core of the CU. Included in the CU are the 8085A CPU, RAM, EPROM, the 8259-5 Programmable Interrupt Controller, dual 8251A USARTs, address decoding circuitry, active bus terminators, and differential transceivers modules [21]. These modules are constructed on small, two-sided printed circuit boards which are then soldered to one of two motherboards (a single motherboard does not provide enough area). A backplane interconnects the motherboards.
Since specifics of the module designs are not part of the work behind this thesis, discussion of the CU hardware will be limited to operational descriptions. Figure 3.14 presents a block diagram of the CU structure.

3.4.1 Central Processing Unit

The 8085A CPU oscillator is set to operate at its maximum speed, 6.144 MHz. The CPU operates upon programs and data stored in ROM and RAM. In the Multi-Micro environment, the CPU may be driven into a hold state by one of the supervisor microprocessors (for DMA), during which programs are downloaded or data is uploaded.

3.4.2 Memory

The memory module has provisions such that a wide variety of both RAM and ROM chips may be used; proper wiring of a few jumpers is required. Maximum storage capacity of a single RAM/ROM module is 16K bytes.

For initial debugging, a single 2716 EPROM (programmed as a system monitor) served as a hexadecimal machine-code interpreter, with 2K bytes of RAM used for scratchpad. The operational CU memory module is comprised of 12K bytes of ROM and 4K bytes of RAM. ROM (specifically, 2716 EPROM's) is programmed with 8K of standard FORTH language [22] and 4K of customized FORTH commands (programs). (FORTH is a unique
language, especially designed for real-time microprocessor based control applications; the structure of the ROM programming and of the FORTH language is examined in Chapter 4.) Two 2Kx8 static RAMs form the 4K of RAM.

Memory requirements are subject to variation; finalization of the Multi-Micro System software may increase or decrease them. If more memory is required (such as if large amounts of data must be stored before unloading), provisions in the CU design allow for the simple addition of another 16K memory module.

3.4.3 Block Selects (Address Decoding)

All peripheral and module accessing is performed through a memory map: the required address decoding is performed by the Block Select module. Both read/write qualified and unqualified strobes are available.

Each strobe output corresponds to a block of addresses; only the higher order address lines are decoded. This permits local decoding of lower order address lines by peripheral components. The PU support logic performs this type of local decoding, as do some other modules of the CU.

3.4.4 Dual USARTs

A dual USART module is included to permit interfacing to a development system. During development and testing
phases, one USART connects to a terminal (via RS-232); the other to a floppy disk drive (via a floppy disk controller). Firmware in FORTH ROMs support the development system interface. Within the operational Multi-Micro environment, the USARTs are inactive.

3.4.5 Interrupt Controller

A 8259-5 Programmable Interrupt Controller prioritizes interrupts and vectors the CPU to the appropriate place in memory for the interrupts's corresponding routine. Three external interrupts are required by the CU. The lowest priority interrupt comes from the PU signaling completion of an integration (either by triggering of the comparator or by the timer TC). Next priority belongs to the Multi-Micro system for the purpose of DMA. The highest priority interrupt comes from the DU via PU buffers signaling that Channeltron input overdrive has occurred. This situation will send the CU into a wait loop until a restart command is given.

3.4.6 CU-PU Interface

Differential transceivers are configured in one-way and two-way modes (as on the PU end) for transmission of the data bus, the lower four address lines, read/write, and two interrupt signals.
The standard transceiver module permits only the transmission of 16 signal lines, without the inclusion of the block select required by the PU local address decoding. As a solution, the block select line is used to enable/disable transmissions through the interface, thus eliminating the need for the transmission of the block select.

3.4.7 Multi-Micro Interface

DMA is not the only means of CU/Multi-Micro interaction. Although the hardware associated with this interface is not considered part of the IDS (or of this thesis), a brief description for perspective's sake is appropriate.

The successful operation of the TQMS Multi-Micro System requires a great degree of real-time communication among all segments (source controller, several mass analyzer controllers, vacuum system, the IDS, and the user) of the system. Several types of registers (or ports) are made available to the IDS (and the other segments), which provide Multi-Micro System information. The IDS is programmed to read and write to these registers. For example, the other segments of the Multi-Micro System are able to adjust mass filters in an asynchronous manner corresponding to the IDS's acquisition of data; system throughput is enhanced.
Speed, compatibility with Multi-Micro software, compactibility of code, simplicity of use, and development ease are all prime considerations relative to the software design. The key to successful implementation of these requirements is based upon the selection of the proper language(s) for this application.

On-line IDS operation is nothing more than the coordination of independent functions of the hardware; "coordination programs" are supplied through the Multi-Micro System and are experiment-dependent. For clarity (and for consistency with the FORTH language as described later), the sub-routines which form the body of the coordinating programs are stored within IDS firmware and are referred to as "commands". This distinction becomes more apparent as this chapter develops.

This chapter begins with a description of the languages chosen for the IDS, their structures, their relationships to hardware, and the reasons behind their selection. Next, descriptions and classification of the commands are presented. Finally, descriptions of the representations used for encoding parameters and data are given. A glossary of all IDS commands is supplied in Appendix B; a source code listing is provided in Appendix C.
"coordinating program" is given in Chapter 5 in conjunction with the evaluation of IDS performance.

4.1 LANGUAGES

Since flexibility of IDS (and TQMS) operation in a real-time mode is required, even to the point where the user can directly actuate fundamental-level hardware operations, a multi-tiered command structure is necessitated. Code written in 8085 assembly language can provide this capability, but programming time requirements are excessively time-consuming and tedious.

The TQMS designers selected the FORTH language [23,24] as a solution to the entire Multi-Micro programming problem. FORTH is especially designed to operate in a real-time microprocessor-based control environment. Except for a few cases where speed requirements are foremost (assembly language is used here), the entire IDS software is written in FORTH.

4.1.1 FORTH

FORTH is an unusual language, primarily since it is all of the following: a high-level language, an assembly language, an operating system, a set of development tools, and a software design philosophy. FORTH is both a compiling and an interpretive language. FORTH code is very compact;
an application system may be operated with a basic FORTH kernel of less than 1K bytes or with the full-feature version of FORTH which requires only 10K bytes. FORTH code also runs fast, typically one-half the speed of equivalent assembly code on an 8-bit microprocessor (such as the 8085).

The FORTH language is stack based; code is written in post-fix notation. As a result, an initial added difficulty faces the programmer in adapting to writing this style of code. Once this adjustment is made, FORTH programming becomes straightforward.

The entire FORTH language is nothing more than a collection of "words", which upon invocation perform their respective functions. A FORTH application program is simply the creation of a new "word", defined in terms of standard FORTH words. These new words may, in turn, be incorporated into still other new words. Henceforth, these applications-defined words are referred to as the "IDS commands".

Features and functions provided by the FORTH language are alluded to throughout the remainder of this chapter. Further information regarding FORTH can be obtained from a variety of sources, including those supplied by references at the end of this thesis.
4.1.2 8085 Assembly Language

On occasion, data must be acquired at a high rate, possibly the result of limited source sample or inefficient ionization. In such cases, standard FORTH words execute too slowly to perform all necessary operations. A pseudo 8085 assembly language is included within the standard FORTH structure, permitting the coding of high-speed operations.

The assembly subset of FORTH is fundamentally identical to actual assembly language. After invocation of a FORTH word which alters the "vocabulary" (the context in which a word is interpreted), the ensuing code is interpreted as assembly language. The "vocabulary" is returned to FORTH upon interpretation of a special character. An assembly routine is called through invocation of an IDS command, whose definition includes the vocabulary change word and the assembly routine. Only a small percentage of the IDS software requires coding in assembly. FORTH code is also more compact than the equivalent assembly code.

4.1.3 Structure

IDS firmware is loaded with standard FORTH words (8K bytes) and IDS commands (4K bytes). "Coordinating programs" and data are stored in RAM (4K bytes). A memory map for the IDS is given in Figure 4.1. The structure of a coordinating program is given in Figure 4.2.
Figure 4.1 IDS Memory Map
Figure 4.2 Coordinating Program Structure
Once an IDS command is defined, it may be used in the definition of another command. Coordinating programs are simply high-level words composed of a sequence of IDS commands and standard FORTH words. The user may execute a word of any level at any time in any sequence; this is the basis for the great degree of flexibility in IDS/TQMS operation.

The firmware is a compiled version of FORTH source code. An interpreter is included within the compiled firmware for interpretation of coordinating programs (the interpreter is one of the standard FORTH words). This interpreter is also very useful in evolving "development commands" (see section 4.2.6) associated with development and testing of the IDS.

4.2 COMMAND CLASSIFICATION

IDS functions are executed through the invocation of IDS commands; all IDS commands are defined in terms of standard FORTH words and/or other IDS commands. These commands fall into one of six classes: elementary functions, standard control, high-speed control, data processing, calibration, and development.

In the source code, some IDS commands are prefixed with a single special character which designates their relationship to hardware for simplified development; renamings are likely in the Multi-Micro environment.
4.2.1 Elementary Function Commands

The CU (Control Unit) of the IDS generates the addresses and control signals which are required by the PU (Processing Unit) for local control strobe generation. The class of commands referred to as "elementary function commands" directs this signal generation.

Functions executed by these commands include:
- setting/resetting of integrator switches and the D/A reference;
- A/D input MUX control, A/D conversion and reading;
- monitor port reading;
- "integration-done" interrupt reset;
- STC (System Timer/Counter) data/command/status loading and unloading;
- and master-reset. The definitions of these commands are very short, since they are simply a read or write to a location in the memory map. All of these commands are incorporated into the definitions of the other IDS commands (coordinating programs rarely require direct use of elementary function commands).

4.2.2 Data Processing Commands

"Data processing commands" execute calculations and conversions upon hardware-collected data and input control parameters. These commands are defined primarily in standard FORTH words which perform arithmetic and logical operations. Data processing commands are usually found in
the definitions of "standard control" and "calibration" commands.

An example of a data processing command, used to calculate the input analog current, is given in Figure 4.3. Here an integration is performed with the STC running a count-down counter to determine the integration time. Upon triggering of the comparator, the timer count is read. This value is placed on the "parameter stack" (see FORTH manual: this LIFO stack is used to supply operands to the IDS commands) by an IDS command. A data processing command called "ZTIME2CUR" accepts this count, along with several other required parameters, and performs the calculation required to convert the count value into the measured current value.

Due to the fact that FORTH provides only integer arithmetics, special programming precautions are taken in performing calculations and conversions to prevent loss of significance. The representations and formatting of parameters and data, which are necessitated by the structure and style of memory and FORTH, are discussed in section 4.3.

4.2.3 Calibration Commands

Two general types of calibration are required of the IDS: adjustments between measuring and threshold setting hardware; and calibration between pulse and analog measuring channels. The former is commonly used in the
The main output current can be calculated by relation:

\[ I = \frac{V - V_{in}}{R} \]

where,

- \( I \): initial current
- \( V \): input voltage
- \( V_{in} \): reference voltage
- \( R \): resistance

Figure 4.3
Data Processing Command example
testing and development phases with external measuring devices to establish absolute hardware operation points. The latter is required in the on-line accurate sampling of an ion input. Examples are as follows:

"OCOMPCHECK", a calibration command, compares the reference input of a comparator to the value of the integrator output which triggered it. The binary value latched into the D/A converter (the comparator reference source) is subtracted from the value read by the A/D converter immediately upon comparator triggering (the A/D automatically performs a conversion anytime the comparator fires). If the result is not equal to the calculated hysteresis of the comparator, an error is signalled. Corrections may be implemented via IDS offsetting of the D/A input, hardware adjustment of an appropriate trimpot, or through software compensation of acquired data values.

A range of ion flux levels, between $10^5$ and $10^6$, provides both pulse and analog current outputs from the Channeltron. By supplying a known ion input to the IDS within this range, "OCHANLDIFF" finds the difference between the ion flux levels calculated from data obtained by each channel.

Calibration commands are defined primarily in terms of elementary function and low-level data processing commands. Calibration commands are found in the definitions of
standard control, high-level data processing, and development commands.

4.2.4 High-Speed Control Commands

For those data acquisition modes where speed is of the essence, a class of "high-speed control commands" are available. These commands simply alter the "vocabulary" and then execute the assembly code contained within their definitions.

An example is the "!MAXSCAN" command. This command instructs the IDS to wait no longer than 100us to collect a single value. The IDS waits for a signal from the TQMS status port to begin integration. Upon receipt of the "start" signal, integration is begun. The timer, which has been set to a maximum of 100us, counts until either the comparator triggers (unlikely) or time expires (a TC signal is generated by the STC). Depending on the input operands to this command, the C/V output, the integrator output, or the timer value is immediately stored, and a "next" signal is sent to the TQMS status port. This procedure continues for a pre-defined number of acquisitions. Note that at this rate of data collection, no data from the pulse channel is usable (see Figure 2.1).

A standard scan procedure is highly similar to the above example, except that more operations may be executed between acquisitions since extra time is allotted. In fact,
most high-speed control commands have a "dual" in a standard control command; but the converse is not true. The Command Glossary notes the duals of these commands. High-speed commands are usually contained in the definitions of high-level, standard control commands.

4.2.5 Standard Control Commands

"Standard control commands" act as the "executive" for the IDS. Sequencing of elementary functions, chaining of data and calibration commands, calling of high-speed routines, programming of references and the STC, I/O communications, and many other operations are executed through standard control commands.

An example of a standard control command is "$ECYCLE". The programming of the STC requires a sequential writing to it of mode, load, and hold register information for each of its five 16-bit counters. By loading the proper code to these registers, counters 1 and 2 are concatenated as a 32-bit timer, counters 3 and 4 are concatenated as a 32-bit pulse counter, and counter 5 is an event counter. "$ECYCLE" takes time limit values (stored in variables by a data processing command), and programming code (stored in firmware "constants"), and performs the correct sequence of write operations to the STC.

The definitions for this class of commands are composed of all other command types. "Standard control commands"
typically compose the majority of commands in a coordinating program.

4.2.6 Development Commands

Development of the IDS is a highly interactive process. It begins with the individual assembly and electrical testing of various modules. These modules are then assembled into the 3 main units of the IDS. Upon demonstration that the CU is electrically and logically operative, EPROMs with standard FORTH code are burned (by another computer) and installed in the CU memory. Interactive development of customized FORTH code on a terminal connected to the CU USART is facilitated, since the standard FORTH code includes an interpreter. All IDS commands are developed in this manner. The debugged commands are retained on a floppy disk (which is connected through the second USART); these commands are eventually compiled and burnt into EPROM. The structure of the FORTH language is extremely conducive to development in this manner.

A set of commands which are useful development aids, but are not required in the operational IDS are classified as "development commands". To aid future testing and maintainance, these commands are also compiled into the CU firmware. Conversion in ASCII output formats for terminal display, looping of strobe signals, and other testing
utilities are included among the development commands. Usage of these commands by the IDS while in the Multi-Micro environment is permitted, but is not particularly useful.

4.3 NUMERIC REPRESENTATION

The standard FORTH words provide only for integer arithmetic. Through proper scaling of control and data parameters, computational and representational errors are avoided. The following sections describe both the internal numeric representations used by the IDS and the representations of parameters and data transmitted through IDS I/O.

4.3.1 Internal Representations

Standard FORTH arithmetic words include provisions for the use of 16 and 32-bit operands. Since the largest number range the IDS deals with is $10^9$, 32 bits is sufficient for IDS programming. For data processing commands which multiply or divide 32 bit numbers, there are standard FORTH words which generate partial products 48 bits in length.

In order to facilitate integer arithmetic, representations which do not require fractions are used. Examples are as follows:

- voltage in millivolts (mV)
- current in picoamperes (pA)
- time in microseconds (μs)
- ion flux in ions/second (ips).
According to the calculations of Chapter 2, none of these values ever exceed $10^9$. Fractional portions are not required since usable IDS parameters and data is at least 100 times greater than a fundamental unit, thus providing sufficient resolution (100:1) over all values.

Rounding errors are avoided primarily because errors of up to 1% (in general) are tolerable. Non-linearities associated with data representing real physical parameters may or may not be taken into consideration, depending on the specific data processing command which is utilized; this distinction is made in the glossary.

4.3.2 I/O Representations

Integer format I/O to system and development terminals often unnecessarily burdens the user. Standard FORTH words provide a solution to this problem: string-to-number and number-to-string conversion words are included in firmware. These words convert an integer to an ASCII string, which can be printed in fractional format at the terminal; an ASCII character representing the radix point is inserted into the appropriate position in the string.

Integer formats of parameters with large ranges of values consume a great deal of memory space (4 bytes per 32-bit number) compared to a floating point format (8 bits of mantissa and 5 bits of exponent provide sufficient resolution and range for the IDS). Data processing commands
which convert an integer to a floating point format are included in the IDS firmware. A shift and count routine is used to perform this function. In cases where high-speed data collection and outputting are being executed, such floating point formatting cannot be done because these operations slow down the data acquisition process.

Some data formats include tag bits with these bits indicating which PU channel, or which A/D input, generated that specific piece of data. This type of tagging is most appropriate for high-speed operations or for hardware calibration. Figure 4.4 depicts the integer and floating point formats; the sequencing of bytes in memory is a characteristic of the 8085 and FORTH structures.
Figure 4.4  Data formats
The Ion Detection System (IDS) is presently in final development stages. Full-scale testing and evaluation require interfacing of the IDS into the TQMS/Multi-Micro System environment, with known ion inputs and their spectra providing benchmarks for complete IDS evaluation. This interfacing will require a significant amount of time, since the Multi-Micro System is yet to be fully developed and tested. Because of the impracticality of full-scale IDS testing in light of current user demands upon the TQMS, and because several adjustments are still required to the IDS (as described later in this chapter), evaluations in this chapter are limited to those from a "bench" environment. Since operation of the Detection Unit (DU) can only be achieved inside of the TQMS vacuum, only the Processing Unit (PU) and the Control Unit (CU) are evaluated here.

This chapter begins with a description of a typical sampling operation. Simulation of this operation is facilitated by the use of a picoampere source in place of the DU (Channeltron) analog output. Following sections highlight the performance of critical circuits; their responses under under sampling simulation are particularly stressed. A final section discusses IDS performance from an overall perspective.
5.1 SAMPLING SIMULATION

The IDS is required to collect up to a maximum of 10000 samples during a single scanning operation (the term "sample" refers to the collection of a single data value corresponding to the ion flux). Programming of the number of samples to be acquired, the data precision, and the maximum sampling time is normally done by the Multi-Micro System through the loading of a coordinating program (see Chapter 4) into the IDS memory. For bench-testing purposes, the IDS is interfaced to a terminal through which a user supplies commands to the on-board FORTH interpreter.

IDS hardware and firmware are responsible for measuring and storing (locally) data values. Once instructed to sample, the IDS normally requires no further interaction with external systems during the sampling period. By simulating this sampling operation, all primary circuit functions can be monitored both through terminal outputs and by external test apparatus.

Since the DU is unavailable for simulation, a picoamper source is substituted for the analog current output of the Channeltron. No simulation of the pulse channel is performed on the bench, since the major component of this channel is a commercially-built module which is specifically designed to operate in conjunction with a channeltron output.

The sequence of IDS commands and parameters, the
The coordinating program, used to perform this simulation is given in Figure 5.1; the development system terminal substitutes for the Multi-Micro System. After initialization, the IDS sends a prompt to the development system terminal, signaling that it is ready to sample. After the picoampere input is set, a command from the terminal initiates a sampling. The IDS returns the C/V converter output voltage, the integrator output voltage, and the integration time to the terminal (instead of an array in memory). These values are logged; the voltage values are compared with externally measured values, and the integration times are plotted to determine linearity in comparison with measured input voltages. This procedure is performed over the entire range of analog inputs.

Several of these simulations are performed, and their results are compared. The variance from ideal expected values is attributed to various circuits; these deviations are discussed in conjunction with their contributing circuits in the next several sections. Figure 5.2 shows several plots of the collected data.

5.2 PROCESSING UNIT (PU) PERFORMANCE

The C/V converter, the integrator, the A/D converter, and the STC (timer/counter) are the key circuits within the analog channel responsible for the precise measurement of DU output currents and conversion into digital data. The
Figure 5.1 Simulation program
Figure 5.2  C/V Converter and Integrator Circuit performance
following sections individually examine the performance of each of these circuits in regard to the simulations.

5.2.1 C/V Converter

Since the C/V Converter must convert currents ranging from 10 pA to .5 uA into voltages ranging from 1 mV to 5 V, small amplitude noise may easily corrupt the signal. The integrator circuit filters a significant amount of mid- and high-frequency noise, but offsets or drifts greater than 1% in the C/V output distort the data by an equivalent amount. This degree of error exceeds design criteria. Interference noise, in the presence of 60 Hz from lab sources, must also be guarded against admission to the integrator input.

Measurements with a DVM and an oscilloscope are performed without the analog board housed in its shielded box (which is presently under construction). As seen in Figure 5.2, C/V output values for low input currents are somewhat offset from the ideal. Specifications for the ICL7650 op-amp show bias currents of 10 pA maximum, not enough to be responsible for the error. Evidence points to the picoampere source as uncalibrated; measurements with an electrometer should validate this conclusion. Interference noise poses a greater problem: sources include 60-cycle, digital generated rf, and the op-amp itself as a result of its chopping action. Oscilloscope measurements show noise up to 50 mV (p-p); data returned by the A/D substantiate
This noise level is significantly reduced from the 100 mV (p-p), which was observed in the circuit before shielding was added to the feedback resistor. Enclosure of the entire circuit board in a shielded housing should further reduce this noise.

5.2.2 Integrator Circuit

Three sub-circuits comprise the integrator circuit: the op-amp integrator, the comparator, and the D/A reference. Evaluations of these sub-circuits are given individually as follows:

The op-amp integrator exhibits a constant offset (0.6%) from its calculated slope of integration; this offset falls easily within the range of allowable component (capacitor and resistor) tolerance error. Also, at low input voltages the integrator output resembles a staircase. This may be the result of the noisy input signal, or the chopping action of the integrator op-amp. Further investigation is required. Enclosure within a shielded box, or capacitive loading of the input may reduce this effect.

No oscillations of the comparator's output are observed at even the slowest threshold crossings. Incorrect triggering of the comparator does occur at slow ramp inputs as a result of the associated staircase effect of the integrator. This provides an explanation for the increasing variation of integration times in conjunction with the
increasing amplitude of the staircase steps. Also, since the 50 mV (p-p) noise common to the entire board is also observed in the comparator input signals, premature triggering of the comparator results. This premature triggering produces integration times which taper away from expected values as the input voltages decrease (see Figure 5.2). It is unlikely that this type of error is the result of circuit leakage currents, unless manufacturer's specifications for components are incorrect.

The D/A converter provides a 0 to 10 V reference ranging in 256 steps (8-bit converter); the analog reference may vary from the desired value by ±19.5 mV. At low reference settings (the reference value represents the minimum-required "analog count", see section 3.3.4), a significant error may result. This error may be compensated for in software by performing a "COMPCHECK" operation (the determination of the actual comparator triggering point) and adjusting collected data values appropriately.

5.2.3 A/D Converter

The 12-bit A/D converter provides a resolution of 1:4096; since a 0-to-10 V range is used, precision to ±1.22 mV is achieved. Since the outputs of the C/V converter and the integrator never exceed 5 V, a 2x gain is applied to the analog signal as it is driven off the analog board to the "D" board, where the A/D converter resides. This makes use
of the full A/D input range (10 V). Lower level signals have increased resolution, while all signals are measured with increased noise margins.

The data generated by the A/D exhibit variations which are partially attributable to simple twisted-pair connection between boards in the development stage (to be replaced with coaxial cables). Also, since input levels are relatively stable over the integration period, no sample-and-hold circuit is included.

5.2.4 STC (System Timer/Counter)

The STC (System Timer/Counter) timer is gated by the same signal which controls the integrator input switch. The time counted by the timer is designed to be exactly equal to the period from which the integration switch was thrown, to the time when the comparator triggers (assuming the timer has not reached its preset maximum limit). Switch delays and jitters contribute insignificant errors, even over minimal integration periods.

5.2.5 Other PU Circuits

All other PU circuits, the support logic, the analog control circuit, and the tranceivers of the PU-CU interface function according to specification. Gating delay times within the logic circuits never add to create a switching
delay (such as with the integrator circuit switches) which could distort the integration time by more than 0.2%, far less than the 1% allowable.

5.3 CONTROL UNIT (CU) PERFORMANCE

The following sections present evaluations of the Control Unit (CU), highlighting software and CU-PU interfacing aspects.

5.3.1 Software

The FORTH-based software facilitates many on-line innovations in the programming of the IL. The commands listed in the glossary are the basic building blocks for the development of customized acquisition modes in IDS operations.

FORTH is extremely valuable as a system-debugging aid. Since commands are developed interactively on the IDS, and since FORTH lends itself well to the establishment of high-level routines, software development is accomplished in an extremely short period of time.

The present set of IDS commands is sufficient for the performance of all basic operations. "High-speed-control commands" (assembly routines) are yet to be written, as they require a closer interaction with the Multi-Micro System. Other command classes also have room for further development
in conjunction with the evolving definition of on-line IDS requirements.

5.3.2 Hardware

The use of a memory-mapped control structure is an effective means of actuating IDS functions. Simple interfacing and programming requirements facilitated debugging and development. The Dual USART's also provide the additional option of sending data to a storage device outside of the Multi-Micro System. The Interrupt Controller's full capabilities are untapped (the IDS only uses 2 interrupts); a simpler interrupt structure may have been used, but with limited expansion capability and elongated development time. CU-PU interface limitations on the number of control lines are successfully circumvented by the use of the interface-enable procedure and local power-on reset circuitry for the PU. All other CU circuits function according to specifications.

5.4 General Observations

The following general observations on IDS performance address the secondary design criteria established in Chapter 2. They include noise immunity, stability and reliability, usability, and cost.
5.4.1 Noise Immunity

As previously demonstrated, the analog circuitry (in its present state) of the IDS is easily corrupted by noise at low input levels. Even upon construction of final IDS housing, additional adjustments may still be required to insure sufficient guarding against unwanted disturbances.

If noise problems still persist, data processing techniques may be employed to compensate for errors. This would be viable, since those inputs which are most affected (low-level signals) require significantly greater integration times. Slow-downs to perform software compensation are negligible compared to integration periods. High-speed data collection only detects high-level signals, which are sufficiently immune to noise.

5.4.2 Stability and Reliability

PU circuit op-amps which provide high-gains require capacitors across their feedback resistors in order to suppress oscillation. Also, if the CMOS op-amps (ICL 7650's) are overdriven, latch-up may occur; protection is provided by zener diodes across feedback paths.

Several components require hardware compensation offsets via trimpots. After initial calibration, components exhibit stable operation. The CMOS analog receivers tend to drift slightly.
ADAPTIVE SAMPLING FOR ENHANCED PERFORMANCE OF AN ION DETECTION -- ETC

JUL 82  R S MATTHEWS, C G ENKE, P D FISHER

N00014-76-C-1092
temperature. Calibration after an appropriate warm-up period compensates effectively.

5.4.3 Usability

The IDS exhibits all the required properties associated with flexibility and user friendliness in operation. The FORTH software provides the framework for this. The tailoring of IDS command mnemonics to resemble the functions which they actuate, facilitates development of user dexterity with the IDS.

From a hardware standpoint, all boards and units connect simply via ribbon cable, coaxial cable, and twisted pair wires. These cables/wires are terminated using standard connectors.
This final chapter provides a general summary of the Ion Detection System (IDS) design goals, implementation, and performance. Further improvements are suggested, and a conclusion relative to the IDS's value to the Triple Quadrupole Mass Spectrometer's (TQMS) Multi-Micro System is provided.

6.1 ACHIEVEMENT OF GOALS

The major goal in undertaking development of the IDS was to create a detection system which operates with optimal efficiency and detection capability. This translates to providing a detector with a dynamic range of $10^9$, and which uses the minimally required integration period (as prescribed by the acceptable error) to acquire a data sample. Combination of a detector of this capability with a Multi-Micro control structure will result in greatly enhanced performance of the Triple Quadrupole Mass Spectrometer.

The expansion of dynamic range is to be achieved through the use of a newly developed Channeltron™ (electron multiplier) in conjunction with appropriate signal-processing electronics (both pulse counting and analog single-slope integration techniques are used).
Testing of the dynamic range capability is still under way. Preliminary results indicate that noise problems, which induce errors greater than 1% to relative precision, exist at low analog signal levels (which provide information about ion flux levels between $10^5$ and $10^9$ ips). Eventual housing of sensitive circuits in a shielded environment should solve this problem. Pulse current detection circuitry (for flux levels less than $10^6$) is yet untested.

The control of asynchronous data acquisition (according to the statistical relationship between the incidence of random ions and the error involved in counting them) is fully implemented and successfully exploits the throughput advantages in this type of scheme. Fundamental firmware which directs hardware operations has been developed and debugged. Further software developments to customize operations and to operate within the Multi-Micro environment may be simply developed using the firmware command kernels (written in FORTH).

Circuitry which performs analog integration exhibits some premature and variant integration time outputs. Although not critical, these variations create errors in excess of 1%. These have been attributed to a defective, specialized IC and to noise problems which permeate the entire board. Again, appropriate shielding measures are being undertaken.
Secondary design goals of stability and reliability, usability, data structures, noise immunity, and cost minimization are only general guidelines in the IDS design. Although evaluations will have to wait until the IDS is operational within the Multi-Micro System, precautions were taken to minimize unwanted effects.

6.2 FURTHER IMPROVEMENTS

Assuming that the prescribed analog circuit adjustments fail to resolve the dynamic range problems, several alternatives exist. One is the replacement of the ICL7650 op-amps with more expensive instrumentation amplifiers, even with the reduced slew rates. New developments in IC technology may possibly provide suitable circuits. Another alternative is the redesign of the analog circuit board to provide increased shielding of individual, critical components. A more complex and costly scheme would involve the use of multiple amplification, integration, and A/D converter stages to segment the analog range portion; various combinations of these circuits could be employed. Also, the use of a dual-slope integration technique could enhance integration precision.

Any further improvements from a design consideration standpoint would first require fundamental improvements in the design of the TQMS itself before increased precision would be meaningful, or increased throughput could be
realized (throughput is statistically limited for a given flux range). The present IDS hardware supplies all necessary circuitry, even for auto-calibration, that is meaningful for this application.

Software enhancements are dependent on the type of acquisitions which may be required. Since FORTH provides more than sufficient flexibility, most software improvements could be made in the development of assembly-coded routines (for high-speed data acquisition), or in the areas of user communications (which would aid the inexperienced user).

6.3 CONCLUSIONS

An ion detection system for a triple quadrupole mass spectrometer, optimally suited for operation within a multi-micro control structure and for data acquisition in the most expedient manner, has been successfully developed. Fundamental to the success of the IDS design is its basis upon the statistical characteristics of the measured quantity (ions), permitting adaptive data sampling for enhanced performance. Although some problems have been identified in preliminary test phases, continuing development is resolving these difficulties. Expectations are that the Ion Detection System (IDS) will provide a greatly enhanced data acquisition capability for the TQMS.
APPENDIX A --- PROCESSING UNIT (PU) CALCULATIONS

The parameter and component values used in the Processing Unit (PU) were calculated as follows:

Defined limits of $5 \times 10^8$ for the maximum ion flux, $\text{IFLX}_{\text{mx}}$, and 1% for the minimum "typical" error (Section 2.1.2). $e_{\text{mn}}$ specify the minimum integration time (Figure 2.1) to be 20 us. To insure 1% accuracy of the timer, 100 non-random counts, $C_{\text{tn}}$, must count the time. Thus a 5MHz source is supplied to the timer. This is generalized as:

$$f_{\text{tmr}} = \text{IFLX}_{\text{mx}} \times e_{\text{mn}}'$$

where $e_{\text{mn}}' = e_{\text{mn}} / 100\%$ and $f_{\text{tmr}}$ = timer source frequency. Thus any flux rate can be calculated:

$$\text{IFLX} = f_{\text{tmr}} / (e_{\text{t}}^2 \times C_t)$$

where $C_t$ = timer counts elapsed during integration period, and $e_{\text{t}}$ = programmed "typical" error for the sample. This error is achieved by integrating until the required amount of ions has been detected (Section 2.1.2).

For the pulse channel, flux determination simply requires counting the discrete current pulses to a
*** APPENDICES ***
set number (related to the error) while simultaneously timing the integration (counting) period.

The analog channel operates in an analogous manner. As described in Section 3.3.4, analog input current can be thought of as chained "charge packets" proportional to the ion flux. A capacitor "counts" this charge to a set voltage while this integration period is timed; this set (or reference) voltage is similarly a function of the programmed error, e' (i.e., charge proportional to 10000 detected ions must be "counted" to achieve 1% accuracy).

The integrator capacitor output voltage is:

\[ V_I = \frac{Q_I}{C_I} \]

Since the maximum "analog count" occurs for the minimum error setting, 1%, the corresponding reference voltage will also be at its maximum. To comply with electrical requirements, this value is chosen to be 5 V. This voltage will represent 10000 ion counts, provided we select proper capacitor and charge amplification components. (Note that linearity is assumed; in reality this is not quite accurate, but software compensates for this.) Lower settings of the reference voltage achieve lesser "counts" (thus greater errors).
The component values are calculated as follows. With $V_A =$ integrator input (C/V output), $R_I =$ integrator input resistor, and:

$$I_I = \frac{V_A}{R_I}$$

then:

$$Q_I = I_I \times t_{int}$$

where $t_{int}$ is the integration time. Figure 2.1 shows that for the maximum flux measured to 1%, a 20 us integration time is required. Also, an input current, $I_A = .5$ uA, is supplied at this flux level (assuming linearity, see Figure 3.3). Since:

$$V_A = I_A \times R_F$$

and:

$$V_I = \frac{(V_A \times t_{int})}{(R_I \times C_I)}$$

then:

$$R_F / (R_I \times C_I) = \frac{V_I}{(t_{int} \times I_A)}$$

$$= \frac{5}{(20 \times 10^{-6} \times 5 \times 10^{-7})}$$

$$= 5 \times 10^{11} \text{F}^{-1}$$

The resistor and capacitor values are chosen to optimize operation against effects of leakage, biases, offsets.
loading, and noise, over the entire input current range.

Practical values chosen are:

\[ R_F = 10 \, \text{M\(\Omega\)} \]

\[ R_I = 20 \, \text{K\(\Omega\)} \]

\[ C_I = 1000 \, \text{pF}. \]
*** APPENDIX B --- COMMAND GLOSSARY ***
Variable: The value which is read out of the timer is stored here (32-bit).

Variable: Holds the combined MSB and LSB of the A/D, right-justified (12 bits in a 16 bit cell).

Variable: Holds a value of the A/D in a decimal, weighted format.

Constant: STC clock frequency.

Constant array: Values define mode register values to be loaded (in STC).

Variable: Holds the timer count-limit, proportional to "MAXTIME".

Variable: The value which is read out of the event counter is stored here (16-bit).

Variable: Holds the calculated value of the scaled, inverse-squared-error.

Constant array: Values define hold register values to be loaded (in STC).

Variable: Holds the calculated elapsed counts of integration.

Variable: Holds the calculated elapsed time of integration (in microseconds).

Variable: Holds the programmed time-limit for integration (in microseconds).

Variable: Holds the programmed error value, an integer between 1 and 100 representing the percent relative standard deviation.

Variable: The value which is read out of the pulse counter is stored here (32-bit).
VLSB DETECTOR 50 2-0 25 FEB 1982
Constant: Represents the value of the A/D least
significant bit, .0024414 V (12-bit A/D over 0-10 V
range). Value is scaled for use in integer arithmetic.

SASTORE DETECTOR 55 4-0 25 FEB 1982
Stores the bytes read from the timer into a variable.
Performs the sequencing required to represent the bytes
as a FORTH 16-bit number.

SEYTER DETECTOR 57 1-0 25 FEB 1982
Loads the LSB followed by the MSB into an STC register.
Used within the "SE CYCLE" routine.

SEV? DETECTOR 58 0-0 25 FEB 1982
Connects, converts, and prints the value of the C/V
converter output (via the A/D).

SECYCLE DETECTOR 54 0-0 25 FEB 1982
Supervises the loading of the STC registers during an
initialization. The master-mode register bit which permits
auto-incrementing of the data-pointer must be active in order
to perform an "element cycle" (see STC data sheet).

SEMIN? DETECTOR 52 1-0 25 FEB 1982
Prints the error-limit value.

SERRORSET DETECTOR 48 1-0 25 FEB 1982
Interprets the top stack value to represent the error-limit
setting for integrations (in integer %). Converts this
into a scaled, inverse-squared-error value (convenient for
later calculations). Stores both values into variables.

SESTORE DETECTOR 55 2-0 25 FEB 1982
Stores the bytes read from the event counter into a variable.
Performs sequencing of the bytes in order to represent a
FORTH 16-bit number.

SEVENTER DETECTOR 54 0-0 25 FEB 1982
Loads the event counter (45) registers; presently not in use.

SHFILER DETECTOR 56 0-0 25 FEB 1982
Coordinates the storing of stack values, representing the
hold register values, into the proper variables.

SHCYCLE DETECTOR 56 0-0 25 FEB 1982
Coordinates the "hold cycle" operation of the STC (reading
the hold registers) and the storing of these values into
variables. The master mode register bit which permits auto-
incrementing must be active for "hold-cycling".

SHODER DETECTOR 53 0-0 25 FEB 1982
Loads the hold registers of the STC. Used within the
"SE CYCLE" routine.

SHCOUNT DETECTOR 49 0-0 25 FEB 1982
Calculates the elapsed integration count by subtracting the
post-integration timer value from the pre-integration timer
value (the count-limit). Stores this result in a variable.
Note: the timer operates in a count-down mode.
SIGTIME DETECTOR 49 0-0 25 FEB 1982
Converts the elapsed integration count value into elapsed integration time (in microseconds). Stores result in a variable.

SINIT-TIME? DETECTOR 58 0-0 25 FEB 1982
Calculates and prints the integration time (in microseconds).

SINIT? DETECTOR 58 0-0 25 FEB 1982
Connect, convert, and print the value of the integrator output (via the A/D).

SLODER DETECTOR 53 0-0 25 FEB 1982
Loads the load registers of the STC. Used within the "SECYCLE" routine.

SNNDER DETECTOR 53 0-0 25 FEB 1982
Loads the mode registers of the STC. Used within the "SECYCLE" routine.

SPSTORE DETECTOR 55 4-0 25 FEB 1982
Stores the bytes read from the pulse counter into a variable. Performs the sequencing required to represent the bytes as a FORTH 32-bit number.

SREADER DETECTOR 56 1-0 25 FEB 1982
Sequentially reads all hold registers (the counter outputs providing a "save" command was issued to the STC) onto the stack.

SRESET-STC DETECTOR 54 0-0 25 FEB 1982
Performs a software reset of the STC.

STIMESET DETECTOR 48 1-0 25 FEB 1982
Interprets the top stack value to represent the time-limit setting for integrations (in microseconds). Converts this value to a count-limit and stores both values into variables.

STMAX? DETECTOR 58 0-0 25 FEB 1982
Prints the time-limit value.

. S DETECTOR 51 0-0 25 FEB 1982
Prints out the contents of the stack non-destructively.

ADCNVRT DETECTOR 46 0-0 25 FEB 1982
Initializes A/D conversion (25 us maximum conversion time).

ADLSB DETECTOR 45 0-1 25 FEB 1982
Reads A/D LSB (and monitor port) and places value on the stack.

ADMSB DETECTOR 45 0-1 25 FEB 1982
Reads A/D HSB output and places value on the stack.

ADOUT? DETECTOR 57 0-0 25 FEB 1982
Prints the binary output of the A/D converter value stored in "#ADCELL".

ADSTART DETECTOR 44 0-1 25 FEB 1982
Constant: Address to start A/D conversion.
ADVEOLTS DETECTOR 57 1-0 25 FEB 1982
Prints the formatted decimal value of the A/D converter value
stored in "ADVEOLTS".

ADWEIGHT DETECTOR 50 0-0 25 FEB 1982
Reads and formats the A/D output bytes into a single cell
(16 bit format, right-justified).

ADLP OUTPUT DETECTOR 45 0-0 25 FEB 1982
Connects C/V output to I/O input via input MUX.

ADINARY DETECTOR 51 0-0 25 FEB 1982
Changes the system number base to 2.

ADTOV DETECTOR 50 3-0 25 FEB 1982
Converts the binary value of the A/D output into a decimal,
weighted format.

ADLOAD DETECTOR 46 1-0 25 FEB 1982
Top stack value is loaded into the STC control port.

ADCTRLPORT DETECTOR 44 0-1 25 FEB 1982
Constant: Address to STC control/status port.

ADLOAD DETECTOR 46 1-0 25 FEB 1982
Top stack value is latched into D/A and the D/A output
follows accordingly.

ADASTART DETECTOR 44 0-1 25 FEB 1982
Constant: Address to load D/A.

ADDATA DETECTOR 44 0-1 25 FEB 1982
Constant: Address to STC data port.

ADLOAD DETECTOR 46 1-0 25 FEB 1982
Top stack value is loaded into the STC data port.

ADDONEACKN DETECTOR 46 0-0 25 FEB 1982
Resets "integration-done" interrupt flip-flop.

ADRECKN DETECTOR 46 0-1 25 FEB 1982
A data register value is read from the STC data port
and placed on the stack. The setting of the data pointer
selects the specific output register; the data pointer is
programmed via the control port.

ADGRATER DETECTOR 44 0-1 25 FEB 1982
Constant: Address to switch integrator output thru the
A/D input MUX.

ADHOLD DETECTOR 45 0-0 25 FEB 1982
Disconnects C/V output from integrator input, i.e. holds
integrator output voltage.

ADINTOOUT DETECTOR 45 0-0 25 FEB 1982
Connects integrator output to A/D input via input MUX.

ADRESET DETECTOR 45 0-0 25 FEB 1982
Zeros integrator output, i.e. integrator reset.

ADRPON DETECTOR 44 0-1 25 FEB 1982
Constant: Address to acknowledge interrupt.
ISTART DETECTOR 45 0-0 25 FEB 1982
Connects C/V output to integrator input, i.e. starts integration.

LSBLATCH DETECTOR 44 0-0 25 FEB 1982
Constant: Address to read A/D LSB and monitor port.

PREAD DETECTOR 46 0-1 25 FEB 1982
Constant: Address to read A/D LSB and status register value is read from STC control/status port and placed on the stack.

SURESET DETECTOR 45 0-0 25 FEB 1982
Resets all switches: S1 open, S2 close, S3 close, S4 open. The integrator is held zeroed with its input disconnected and with its output connected to the A/D input.

SWSTART DETECTOR 44 0-1 25 FEB 1982
Constant: Address to switch reset.

UD. DETECTOR 51 1-0 25 FEB 1982
Prints out the top stack value (if a 32-bit number) in an unsigned format.
*** APPENDIX C --- SOURCE CODE ***
Block Number: 44
0 (PU ADDRESS MAP—CHIP SELECTS)
1 MEX
2 BF80 CONSTANT LSBLATCH
3 BF80 CONSTANT MSBLATCH
4 BF82 CONSTANT S4OPEN
5 BF84 CONSTANT S4CLOSE
6 BF86 CONSTANT S5OPEN
7 BF88 CONSTANT S5CLOSE
8 BF8A CONSTANT IRPTOFF
9 BF8E CONSTANT DATAPORT
10 BF8F CONSTANT CNTRLPORT

Block Number: 45
0 (ELEMENTARY HARDWARE COMMANDS)
1 ADPCONV PRE-AMP C0 DROP ; (CONNECTS PRE-AMP TO A/D INPUT)
2 SWITCH 1 CLOSED, SWITCH 2 OPEN
3 INTOUT INTEGRATOR C0 DROP ; (CONNECTS INTEGRATOR TO A/D)
4 INPUT, SWITCH 2 CLOSED, SWITCH 1 OPEN
5 IRESET S4CLOSE C0 DROP ; (RESUMES INTEGRATOR OUTPUT)
6 ISET S4OPEN C0 DROP ; (FLOATS INTEGRATOR OUTPUT)
7 ISTART 0 S4CLOSE C0 DROP ; (CONNECTS PRE-AMP TO INTEGRATOR)
8 HSTART S5OPEN C0 DROP ; (DISCONNECTS PRE-AMP FROM INTEGRATOR)
9 SRESET S5CLOSE C0 DROP ; (SETS ALL SWITCHES TO POWER-UP)
10 STATE, SWITCHES 1 AND 4 OPEN, SWITCHES 2 AND 3 CLOSED
11 ADMSB LSBLATCH C0 ; (A/D OUTPUT AND MONITOR REGISTER)
12 DCON-DOX 12;004 --> STACK

Block Number: 46
0 (ELEMENTARY HARDWARE COMMANDS)
1 ACHVNT DASTART C2 ; (INITIATES A/D CONVERSION)
2 DLOAD DASTART C3 ; (STACK --> D17-D10, SETS D/A)
3 DONEACKN 0 IRPTOFF C3 ; (SETS DONE INTERRUPT)
4 CLOAD CNTRLPORT C3 ; (STACK --> STC CONTROL PORT)
5 DLOAD DATAPORT C3 ; (STACK --> STC DATA PORT)
6 BREAD CNTRLPORT C3 ; (STC STATUS REGISTER --> STACK)
7 DREAD DATAPORT C3 ; (STC DATA PORT --> STACK)

Block Number: 47
0 (DATA PROCESSING VARIABLES AND CONSTANTS)
1 DECIMAL
2 (STC clock frequency)
3 5.000;000 2CONSTANT #CLOCK
4 (Date parameter variables)
5 VARIABLE SHTIME1
6 VARIABLE SHTIME2
7 VARIABLE SHTIME3
8 VARIABLE SHTIME4
9 VARIABLE SHTIME5
10 VARIABLE SHTIME12
11 VARIABLE SHTIME13
12 VARIABLE SHTIME14
13 VARIABLE SHTIME15
14 VARIABLE SHTIME16
Block Number: 48
0 ( PARAMETER SETTING )
1 DECIMAL
3 ( Convert time-limit into count-limit )
5 : $TIMESET 2DUP MAXTIME 2! $CLOCK 1000 M/ 1000 M/
6 : $COUNTMAX 2! ;
7 ( Convert error-limit into inverse-error-squared )
9 : $ERRORSET DUP MINERROR : DUP + 10000 SWAP /
10 : MERSINV ! ;

Block Number: 49
0 ( PARAMETER CALCULATIONS )
1 DECIMAL
3 ( Calculate elapsed counts during integration period )
5 : $COUNT $COUNTMAX 28 $ACCOUNT 28 $-
6 : $COUNTMAX 2! ;
7 ( Convert elapsed counts to elapsed time in us )
9 : $SIGTIME $COUNTMAX 21 $CLOCK 1000 M/ 1000 / M/
10 : $SIGTIME 2! ;

Block Number: 50
0 ( A/D RELATED )
1 DECIMAL
3 ( A/D LSB Volts = .0024414 Volts )
5 : 24414 CONSTANT $VLSB
7 ( A/D variables )
8 : VARIABLE $BADCELL
9 : VARIABLE $BADVOLTS
11 ( Format A/D bytes into single cell )
12 : ADMEIGHT ADMSB 16 + ADLSB 16 / $BADCELL ! ;
13 ( Multiply A/D binary output x LSB value )
15 : STOV $VLSB $BADCELL 8 $M 10000 M/ $BADVOLTS ! ;

Block Number: 51
0 ( UTILITIES )
1 HEX
3 ( Non-destructive stack printout )
5 : $ CR 'S 50 1 0 - DO I 0 -2 +LOOP ;
6 ( Set base to binary )
8 : $BINARY 2 BASE ! ;
9 ( Print unsigned 32-bit number from stack )
11 : UD (8 9 8 8) TYPE ;
Block Number: 52
( STC REGISTERS’ ASSIGNMENTS )
1
2 ( Counters 1 and 2 are concatenated as a single 32-bit 
3 counter, as are counters 3 and 4; counter 5 is used as an 
4 event counter. Counters 1-4 are programmed in operating 
5 mode “B” with active low gate, 5MHz source, and active 
6 low TC. Counter 5 is programmed in operating mode “A” 
7 with TC inactive, output low. )
8
HEX
9
10 ( Mode registers’ assignments: )
11 CREATE $CMR 005 $BOO3 $BBO5 $BOO5 $OBOO .
12
13 ( Hold registers’ assignments: )
14 CREATE $HLR 0000000 .
15
Block Number: 53
0 ( STC INITIALIZATION )
1
2 HEX
3
4 ( Load LSB followed by MSB into the STC registers )
5 $SBYTE: DUP CE $LOAD 0 CE $LOAD ;
6
7 ( Load “mode” register with firmware values )
8 : $MOODER 1’ 2 = $CMR + $SBYTE ;
9
10 ( Load “load” register with programmable count-limit values )
11 : $LOADER 1’ 2 MOD IF = $COUNTMAX $SBYTE 
12 ELSE = $COUNTMAX 2’ $SBYTE THEN ;
13
14 ( Load “hold” register with firmware values )
15 : $MOODER 1’ 2 = $HLR + $SBYTE ;
16
Block Number: 54
0 ( STC INITIALIZATION )
1
2 HEX
3
4 ( Event counter loader: presently not in use )
5 : $EVENTER 10 DROP ;
6
7 ( Software reset STC )
8 : $RESETSTC FF $LOAD 0F $LOAD ;
9
10 ( Initialize STC by performing element cycle )
11 : $ECYCLE 01 $LOAD 40 DO $MOODER $LOADER $MOODER LOOP 
12 : $EVENTER ;
13
14
15
Block Number: 55
0 ( STC READING )
1
2 HEX
3
4 ( STC Counter output variables )
5 VARIABLE $ACCOUNT ( Event count )
6 VARIABLE $PCOUNT 2 ALLOT ( Pulse count )
7 VARIABLE $ACOUNT 2 ALLOT ( Timer-analog count )
8
9 ( Store counter outputs, on stack, into memory )
10 : $STORE 0 I DO 1 2 MOD $ACCOUNT + C! -1 +LOOP ;
11 : $GSTORE 2 5 DO 1 4 MOD $ACCOUNT + C! -1 +LOOP ;
12 : $PSTORE 2 5 DO 1 4 MOD $ACCOUNT + C! -1 +LOOP ;
13 ( Bytes on stack are sequenced into FORTH-compatible 
14 representations for 16- and 32-bit numbers )
Block Number: 56
0 ( STC READING )
1
2
3
4
5
6
7
8
9
10
11
12
13
14
15

Block Number: 57
0 ( I/O )
1
2
3
4
5
6
7
8
9
10
11
12
13
14
15

Block Number: 58
0 ( I/O )
1
2
3
4
5
6
7
8
9
10
11
12
13
14
15

Execute "hold" cycle, put all values on the stack
$READER 19 LOAD A 0 DO DREAD LOOP ;

File the values from the stack into memory
$FILER RESTORE $STORE $STORE $STORE ;

Read and store "hold" register values
$MCYCLE $READER $FILER ;

Print the decimal A/D output value
ADVOLTS? BASE 0 STDV ADVOLTS 0 DECIMAL 0 < & $ = &
46 HOLD 0 $ TYPE SPACE "V" BASE ;

Print the monitor port status, in bits
MPORT? BASE 0 ADLSB 16 MOD BINARY
... " (NO-NO) " BASE ;

Print the time-limit or error-limit setting
STMAX? MAXTIME 28 UD. " us " ;
MIN? MINERROR % " % " ;

Print the elapsed integration time
SINT? SIGTIME SIGTIME 28 UD. " us " ;

Connect, convert, and print the C/V or integrator output
SCV? AMPOUT ADCHRT ADVOLTS ;
SINT? INTOUT ADCHRT ADVOLTS ;


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8-8